

an array of wire bond connections electrically connected to the solder ball array connections;

wherein known good integrated circuit device testing is completed prior to mounting the integrated circuit device on an end use device by connecting a test device by wire bond connections or by solder ball connections; and

wherein when either the wire bond connections are used or the solder ball connections are used for known good integrated circuit device testing, the other is available for connection to an end use device.

Please cancel claims 11 - 43.

IN THE DRAWINGS:

Please make the changes marked in red on the sheets of drawings attached to the accompanying Letter to the Official Draftsperson.

REMARKS

This amendment cancels the claims in Group II (claims 11 - 43). Applicant now wishes to prosecute Group I (claims 1 - 10)

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with Marking to Show Changes Made."